

AMENDMENTS TO THE SPECIFICATION:

Please replace the title with the following amended title:

“PRESSURE CONTACT SPRING FOR [[A]] CONTACT ARRANGEMENT IN [[A]]
POWER SEMICONDUCTOR MODULE”

Please add the following new paragraph immediately after the title appearing on
page 1.

This disclosure claims priority under 35 USC § 371 to International Application No.
PCT/CH2003/000569, filed August 22, 2003, the contents of which are incorporated herein
by reference.